Title (en)

Method of molding a molding resin on a substrate having openings and switch substrate with a molding resin

Title (de)

Verfahren zum Formen eines Formharzes auf einem Substrat mit Öffnungen und Schaltersubstrat mit einem Formharz

Title (fr)

Procédé pour mouler une résine de moulage sur un substrat pourvu de trous et substrat de commutateur pourvu d'une résine de moulage

Publication

EP 1013391 B1 20030409 (EN)

Application

EP 99310445 A 19991222

Priority

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Abstract (en)

[origin: EP1013391A2] A substrate (10), a first mold (200) and a second mold (250) are prepared, and a plurality of switch patterns (14), (18) are provided by providing openings (pattern-removal portions) (A) in such a manner that a pattern (11), which has been formed on the surface of the substrate (10), is divided into a plurality of patterns. A switch substrate (1) is formed as a result. Next, the switch substrate (1) is clamped between the first mold (200) and the second mold (250). At such time the side of the switch substrate (1) provided with the switch patterns (14), (18) is brought into surface contact with an abutting surface (201) of the first mold (200) and, at the same time, a cavity (253) provided in the second mold (250) is made to oppose the other side of the switch substrate. Next, a molten molding resin is charged into the cavity (253) provided in the second mold (250) to thereby fill the cavity (253) and the openings (A) of the substrate with the molding resin. After the molding resin hardens, the first mold (200) and the second mold (250) are separated and the switch substrate (1), which will have the molding resin (a case 40) attached thereto, is extracted. <IMAGE>

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IPC 8 full level

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